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| <p align="center">REQUEST FOR CONTINUED EXAMINATION (RCE) TRANSMITTAL</p> <p>Subsection (b) of 35 U.S.C. §132, effective on May 29, 2000, provides for continued examination of an utility or plant application filed on or after June 8, 1995. See The American Inventors Protection Act of 1999 (AIPA).</p> | Application Number | 09/736,225 |
| | Filing Date* | December 15, 2000 |
| | First Named Inventor | HUANG et al. |
| | Group Art Unit | 2811 |
| | Examiner Name | N. Parekh |
| | Attorney Docket No. | REF/HUANG/6315/225 |

This is a Request for Continued Examination (RCE) under 37 C.F.R. §1.114 of the above-identified application.

NOTE: * Filing date must be on or after June 8, 1995; but if before May 29, 2000, then consider a CPA.

1. Please consider the following as the required submission under 37 C.F.R. §1.114:

- ☒ a. The Amendment/Reply filed on (date): January 21, 2003
- ☐ b. The Information Disclosure Statement (IDS) filed on (date):
- ☐ c. The arguments in the Brief/Reply Brief filed on (date):
- ☐ d. The ___ page(s) of Form PTO-1449 and copy of each listed document filed (date):
- ☐ e. Other:
- ☐ 2. A _____ month Petition for Extension of Time is filed herewith.
- ☒ 3. The Commissioner is authorized to credit any overpayment and charge any deficiency in any fees required under 37 CFR 1.16 and/or 1.17 to Deposit Account No. 02-0200.
- ☒ 4. A check in the amount of \$ 750.00 is submitted herewith.
- ☐ 5. This Request is transmitted by facsimile to number (703) _____.
- ☐ 6. Other:

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|--|----|--------------------|----|--|------|--|----------|
| THE RCE FEE IS CALCULATED AS FOLLOWS: | | | | | | Basic Fee: | \$750.00 |
| Total Claims: | 14 | - | 20 | (highest number previously paid for) = | 0.00 | X \$18 = | 0.00 |
| Independent Claims: | 2 | - | 3 | (highest number previously paid for) = | 0.00 | X \$84 = | 0.00 |
| Correspondence Address: BACON & THOMAS, PLLC 625 Slaters Lane, 4 th Floor Alexandria, VA 22314-1176  23364 PATENT TRADEMARK OFFICE | | | | | | Multiple Dependent Claim (add \$280.00): | |
| | | | | | | Subtotal: | \$750.00 |
| | | | | | | 50% Reduction if Small Entity Status: | |
| Phone: 703-683-0500 Fax: 703-683-1080 | | | | | | Total: | \$750.00 |
| Date: | | Name: | | Signature: | | Reg. No. | |
| January 21, 2003 | | Richard E. Fichter | | <i>Richard E. Fichter</i> | | 26,382 | |

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

HUANG et al.

Group Art Unit: 2811

Serial No.: 09/736,225

Examiner: N. Parekh

Filed: December 15, 2000

For: SEMICONDUCTOR PACKAGE WITHOUT SUBSTRATE
AND METHOD OF MANUFACTURING SAME#11/C
3-10-03
Payton**AMENDMENT**Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

This is further to the Notice of Appeal in connection with the above-identified application. The appeal brief is due on January 18, 2003. A Request for Continuing Examination (RCE) and amendment are submitted along with the appropriate fee. The filing of the RCE avoids the necessity of preparing an appeal brief.

Please amend the above-identified application as follows.

IN THE CLAIMS:

Please cancel claims 17 to 30 without prejudice or disclaimer and add the following new claims to the application.

Sub D1
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31(New). A single semiconductor package consisting of an unsupported single layer linearly consisting of at least two solder mask portions formed at selected locations, and between and adjacent said solder mask portions is a die pad portion of said layer contiguous to each solder mask portion; and lead portions of said layer adjacent to and contiguous to said solder mask portions, said die pad has a chip adhering to the die pad surface; a plurality of conductive elements are electrically